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Part Number: **0676430980**
Status: **Active**
Description: Universal Serial Bus (USB) Shielded I/O Receptacle, Right Angle, Type A, High-Temperature Black Nylon, Gold (Au) Flash Plating, PCB Thickness 1.20mm (.047"), with Upper Flange, for IR Reflow Process, Lead Free

Documents:

[3D Model](#) [Product Specification PS-67643-003 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

General

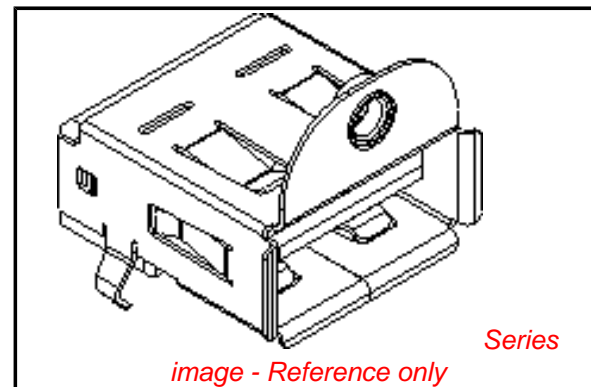
Product Family	I/O Connectors
Series	67643
Application	Wire-to-Board
Comments	With Upper Flange For IR Reflow Process
Component Type	Receptacle
Product Name	USB
Type	A

Physical

Boot Color	N/A
Circuits (Loaded)	4
Circuits (maximum)	4
Gender	Receptacle
Keying to Mating Part	Yes
Lock to Mating Part	Yes
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Number of Rows	1
Orientation	Right Angle
PC Tail Length (in)	0.079 In
PC Tail Length (mm)	2.00 mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness Recommended (in)	0.045 In
PCB Thickness Recommended (mm)	1.20 mm
Packaging Type	Tray
Panel Mount	Yes
Pitch - Mating Interface (in)	0.079 In, 0.098 In
Pitch - Mating Interface (mm)	2.00 mm, 2.50 mm
Pitch - Term. Interface (in)	0.079 In, 0.098 In
Pitch - Term. Interface (mm)	2.00 mm, 2.50 mm
Polarized to Mating Part	Yes
Polarized to PCB	Yes
Ports	1
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	0°C to +50°C
Termination Interface: Style	Through Hole
Waterproof / Dustproof	No

Electrical

Current - Maximum per Contact	1.5A
Shield Type	Full Shield
Shielded	Yes
Voltage - Maximum	30V DC



EU RoHS

**ELV and RoHS
Compliant**
REACH SVHC
 Not Reviewed
**Halogen-Free
Status**

China RoHS



**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

67643Series

Mates With

USB Type A Plug

Solder Process Data

Lead-free Process Capability
Process Temperature max. C

SMC & Wave Capable (TH only)
260

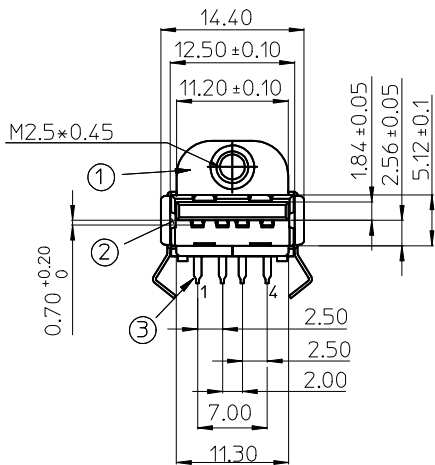
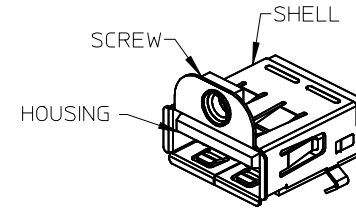
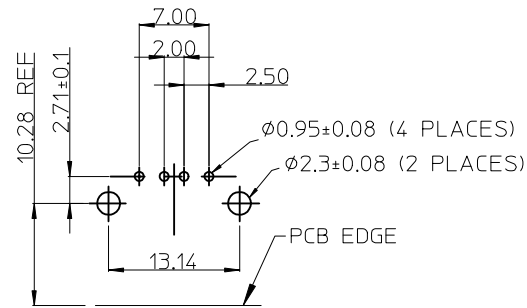
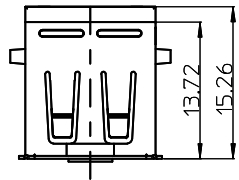
Material Info**Reference - Drawing Numbers**

Product Specification
Sales Drawing

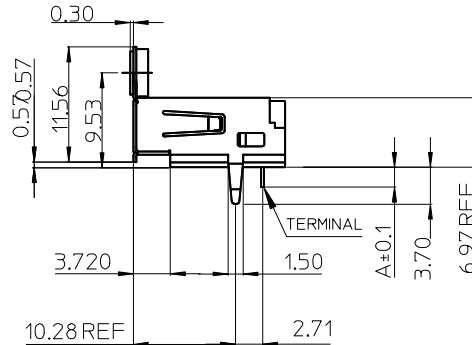
PS-67643-003
SD-67643-004

This document was generated on 03/31/2010

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PCB LAYOUT (BOTTOM VIEW)



NOTES:

1. MATERIAL:
 - ① METAL SHELL: COPPER ALLOY. SCREW: BRASS
 - ② HOUSING: SEE CHART, 30% GLASS FIBER FILLES, UL94-V0.
 - ③ TERMINAL: PHOSPHOR BRONZE
2. PLATING:
 - TERMINAL:
 - CONTACT AREA: (a) GOLD FLASH.
 - (b) GOLD (Au), THICKNESS=30 MICROINCH MINIMUM.
 - SOLDER TAIL: TIN PLATED, THICKNESS=75 MICROINCH MINIMUM.
 - UNDER PLATED: NICKEL (Ni), THICKNESS=50 MICROINCH MINIMUM.
 - METAL SHELL: SEE CHART.
3. RECOMMENDED PCB THICKNESS: SEE CHART
4. PRODUCT SPECIFICATION: FOR IR REFER TO PS-67643-002
FOR NON IR REFER TO PS-67643-003
5. TORQUE FORCE SPEC: 2.50kg-cm Min, MEASURED AT BROKEN POINT.
6. TEST SUMMARY: FOR IR REFER TO TS-67643-002
FOR NON IR REFER TO TS-67643-003
7. PACKAGE: REFER TO PK-67643-002
8. LEAD FREE AND ROHS COMPLIANCE PRODUCT

REVISED	EC NO: D	DRWN: YPWU CHKD: APPR:	2009/08/28	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION				
					▼=0 ◻=0			MM ONLY		1:1	METRIC		TITLE USB A TYPE RCPT SGL RA THRHOLE WITH UPPER FLG (LEAD-FREE VERSION) MOLEX INCORPORATED			
								mm	INCH	DRAWN BY	DATE				DOCUMENT NO. SD-67643-004	
								DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 2	SHEET NO. 1 OF 2					
				ANGULAR ± 3 °		DRAWN BY: IVY-LIN DATE: 2005/04/01 CHECKED BY: ALL IN DATE: 2005/04/01 APPROVED BY: WWSCHANG DATE: 2005/04/01		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

7 6 5 4 3 2 1

P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK
67643-0990	POLYESTER	BLACK	GOLD FLSAH	IR REFLOW PROCESS MATTE TIN PLATED AT SOLDER AREA THICKNESS=100 MICROINCH MINIMUM UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE)	NON IR
67643-1990	POLYESTER	WHITE			REFLOW PROCESS
67643-2990	HIGH TEMPERATURE NYLON	BLACK			FOR IR
67643-3990	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS
67643-0991	POLYESTER	BLACK	GOLD PLATING 30 MICROINCH	NON IR REFLOW PROCESS: MATTE TIN PLATED. THICKNESS=80 MICROINCH MINIMUM UNDER PLATE:NICKEL (Ni).	NON IR
67643-1991	POLYESTER	WHITE			REFLOW PROCESS
67643-2991	HIGH TEMPERATURE NYLON	BLACK			FOR IR
67643-3991	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS
PCB THICKNESS		1.60±0.05			
DIMENSION "A"		2.60			

P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK
67643-0980	HIGH TEMPERATURE NYLON	BLACK	GOLD FLSAH	IR REFLOW PROCESS MATTE TIN PLATED AT SOLDER AREA THICKNESS=100 MICROINCH MINIMUM UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE)	FOR IR
67643-1980	HIGH TEMPERATURE NYLON	WHITE			
67643-0981	HIGH TEMPERATURE NYLON	BLACK	GOLD PLATING 30 MICROINCH		
67643-1981	HIGH TEMPERATURE NYLON	WHITE			
PCB THICKNESS		1.20±0.05			
DIMENSION "A"		2.00			

REVISED ECT NO: D DRWN: YPWU CHKD: APPR:	2009/08/28 DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± 0.25 ± --- ANGULAR ± 3 °	DIMENSION STYLE MM ONLY DRAWN BY DATE IVY-LIN 2005/04/01 CHECKED BY DATE ALL IN 2005/04/01 APPROVED BY DATE WWSCHANG 2005/04/01 MATERIAL NO.	SCALE 1:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE USB A TYPE RCPT SGL RA THRHOLE WITH UPPER FLG (LEAD-FREE VERSION)		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE TABLE	MOLEX INCORPORATED DOCUMENT NO. SD-67643-004	SHEET NO. 2 OF 2	
					SIZE A4	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

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